g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-DS200TBQCG1A**

Test Procedure for a Terminal Board (R-S-T) Analog I/O

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	Steve Pharris	07/07/09
B	Adjusted step 6.1.1, increased voltage level to test regulators true output voltage(s)	J. Barton	8/21/12
C	Added section 6.3 about card burn instructions	G. Chandler	12/13/2013

PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
Steve Pharris	J. Barton	G. Chandler	Charlie Wade
DATE	**DATE**	**DATE**	**DATE**
07/07/09	8/21/12	12/13/2013	7/7/2009

1. SCOPE

1.1 This is a functional testing procedure for a DS200TBQCG1A.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 DS200TBQC SH 4AA-4DA

3.1.2 Check board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		DC Power Supply

6. TESTING PROCESS

6.1 Setup

6.1.1 Set power supply to 26.5VDC

6.1.2 Connect common from power supply to TEST9

6.1.3 Connect + from PS to JFR33

6.2 Testing Procedure

6.2.1 Apply power to card

6.2.2 Check for ~24VDC at TEST1-TEST8

6.2.3 Move + from power supply to JFS33

6.2.4 Repeat step 6.2.2

6.2.5 Move + from power supply to JFT33

6.2.6 Repeat step 6.2.2

6.2.7 Verify short between JFR33 and JBR39

6.2.8 Verify short between JFS33 and JBS39

6.2.9 Verify short between JFT33 and JBT39

6.2.10 Component test remainder of card.

6.3 Burn-in for card

6.3.1 Connect +27vdc to JBR-39 with common to JBR-40.

6.3.2 Connect 470 ohm 2w resistors from common to the following points.

6.3.3 TB1-37, TB1-43, TB1-49, TB1-55, TB1-61, TB1-67, TB1-73.

6.3.4 Verify +24vdc +/- 1vdc at each of the TB1 connections

6.3.5 Normal repairs; burn card in for 1 hours and verify +24vdc +/- 1vdc at each of the TB1 connections.

6.3.6 **All Revitalization Cards shall be burned-in for three (3) hours, check text box in SAP to determine if they fall into this category.**

*6.4 **TEST COMPLETE ****

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.